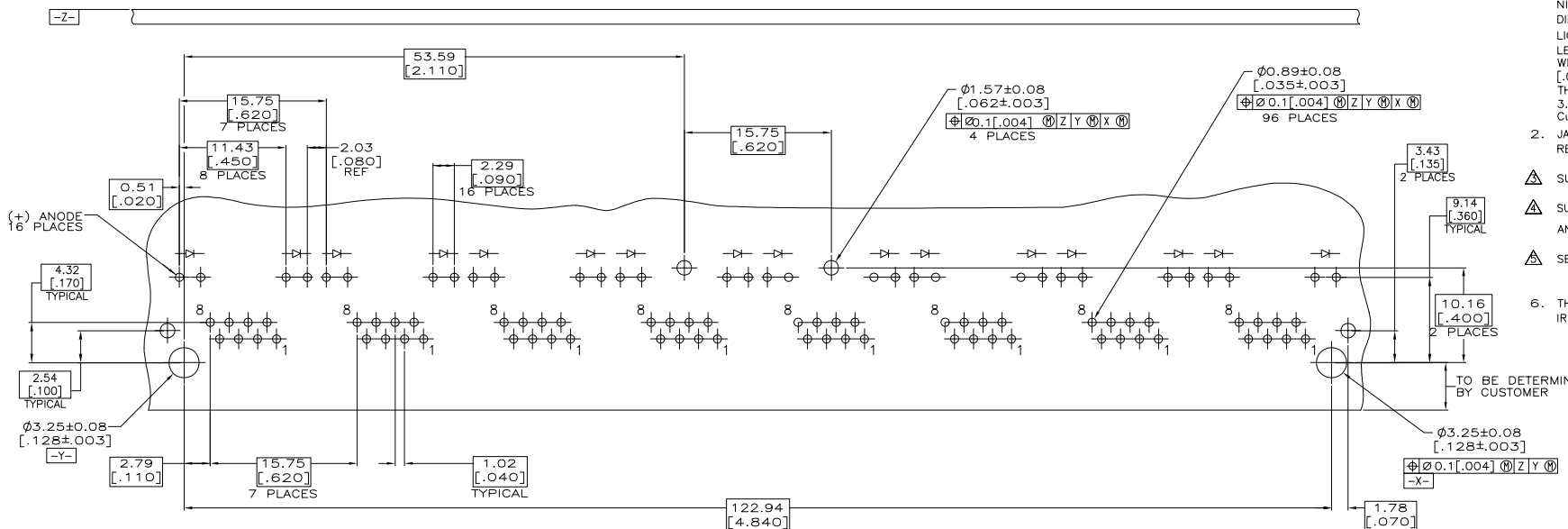
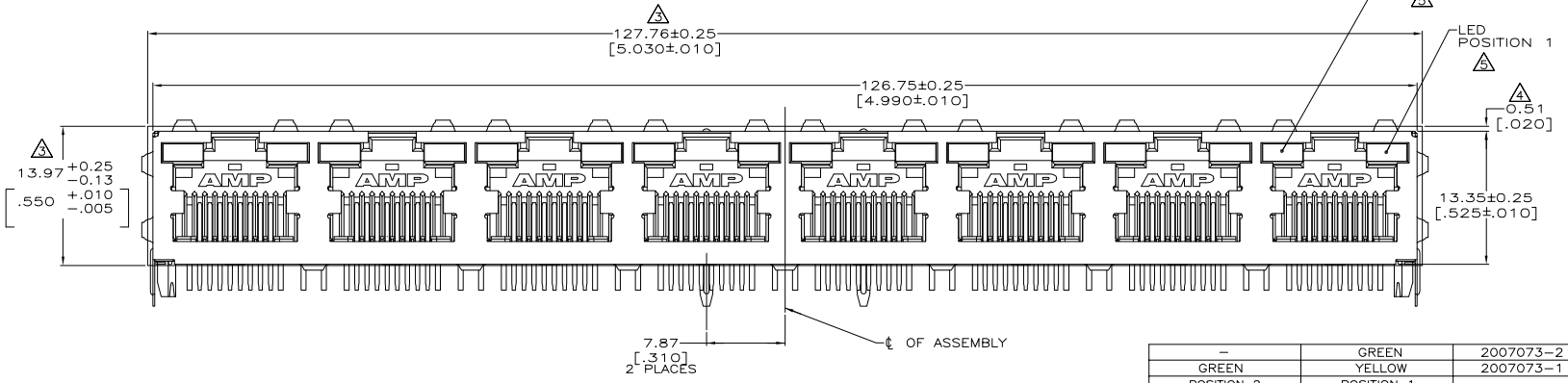
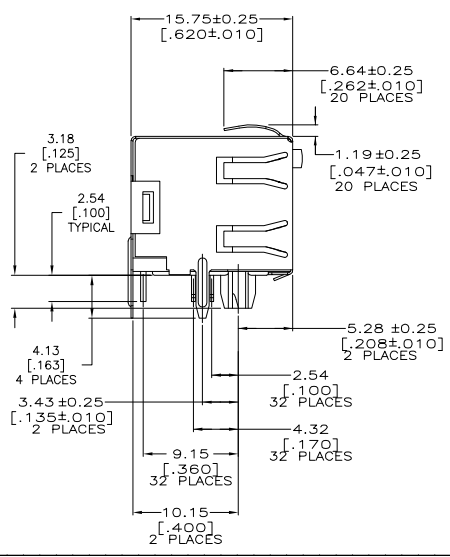


- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27 μ m[.000050] MIN THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μ m [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MIN THICK NICKEL UNDERPLATE. CONTACT LUBE ON GOLD PLATED PORTION
 SHIELD - 0.196[.0077] THICK COPPER ALLOY PREPLATED WITH 1.27 μ m[.000050] MINIMUM SATIN NICKEL WITH 2.03 μ m[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μ m [.0003500] THICK Sn/Cu OVER 2.03 μ m[.000080] THICK Ag OVER 1.02 μ m[.000040] THICK Cu 3.56 μ m[.000140] THICK Ni OVER 1.02 μ m[.000040] Cu UNDERPLATE.
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
 - △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
 - △ SEE TABLE FOR COLOR OF LEDS.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 COMPONENT SIDE



-	GREEN	2007073-2
GREEN	YELLOW	2007073-1
POSITION 2	POSITION 1	PART NUMBER
INDICATOR COLOR FOR EACH HOUSING		

THIS DRAWING IS A CONTROLLED DOCUMENT.

DWG NO. 108-1163-4	REV. 1	DATE 11/14/08	BY J. BLICKINGER
CHK. J. WESTMAN	APP. J. WESTMAN	DATE 11/14/08	BY J. BLICKINGER
PRODUCT SPEC. 108-1163-4	APPLICATION SPEC. 114-2154	SIZE A1	CODE 00779
MATERIAL -	WEIGHT -	SCALE 4:1	SHEET 1 OF 1

INVERTED MODULAR JACK ASSEMBLY, 1X8, SHIELDED, BOTTOM TAB, PANEL GROUND, LED

SEE NOTE 1